

Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PK}	30	W
Peak Pulse Current ($t_p = 8/20\mu s$)	I_{PP}	4	A
ESD per IEC 61000-4-2 (Air) ⁽¹⁾ ESD per IEC 61000-4-2 (Contact) ⁽¹⁾	V_{ESD}	± 16 ± 14	kV
Operating Temperature	T_J	-40 to +85	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Characteristics ($T=25^\circ C$ unless otherwise specified)

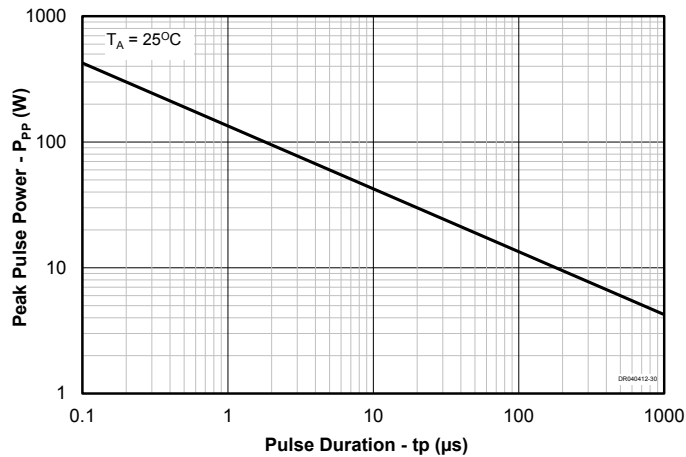
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Reverse Stand-Off Voltage	V_{RWM}				3.3	V
Punch-Through Voltage	V_{PT}	$I_t = 50\mu A$	3.65	4	4.4	V
Snap-Back Voltage	V_{SB}	$I_{SB} = 50mA$	2.8			
Reverse Leakage Current	I_R	$V_{RWM} = 3.3V$		<1	50	nA
Clamping Voltage	V_C	$t_p = 8/20\mu s$	$I_{PP} = 1A$		5.5	V
			$I_{PP} = 3A$		6.5	
			$I_{PP} = 4A$		7.5	
ESD Clamping Voltage ²	V_C	$t_p = 0.2/100ns$	$I_{PP} = 4A$	6		V
			$I_{PP} = 16A$	8.5		
Dynamic Resistance ^{2,3}	R_{DYN}	$t_p = 0.2/100ns$		0.21		Ω
Junction Capacitance	C_J	$V_R = 0V, f = 1MHz$ $T = 25^\circ C$		6	9	pF

Notes

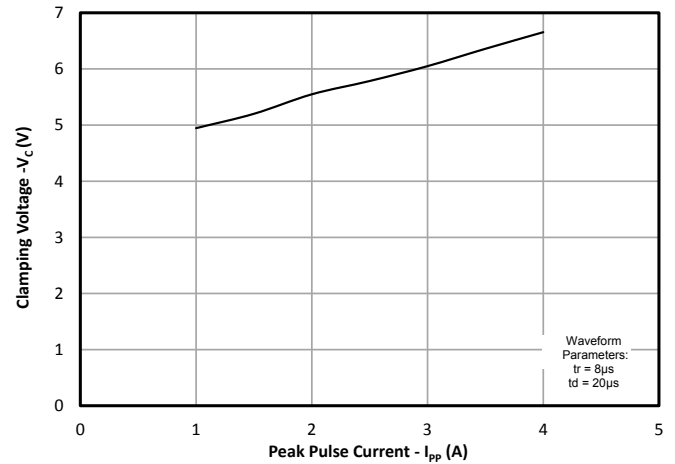
- 1) ESD gun return path connected to ground reference plane.
- 2) Transmission Line Pulse Test (TLP) Settings: $t_p = 100ns$, $t_r = 0.2ns$, I_{TLP} and V_{TLP} averaging window: $t_1 = 70ns$ to $t_2 = 90ns$.
- 3) Dynamic resistance calculated from $I_{TLP} = 4A$ to $I_{TLP} = 16A$.

Typical Characteristics

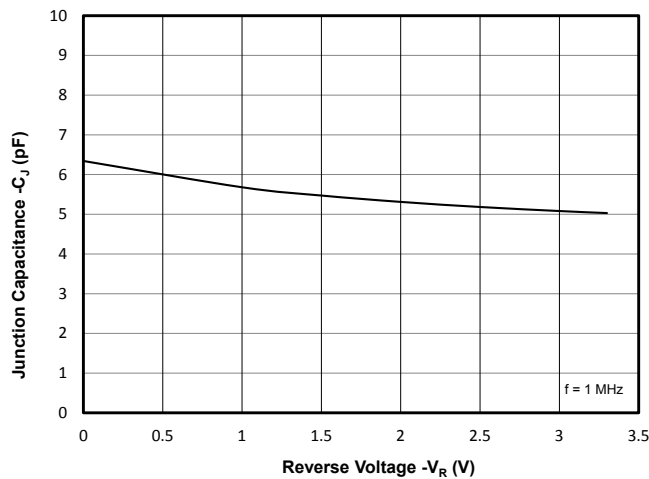
Non-Repetitive Peak Pulse Power vs. Pulse Time



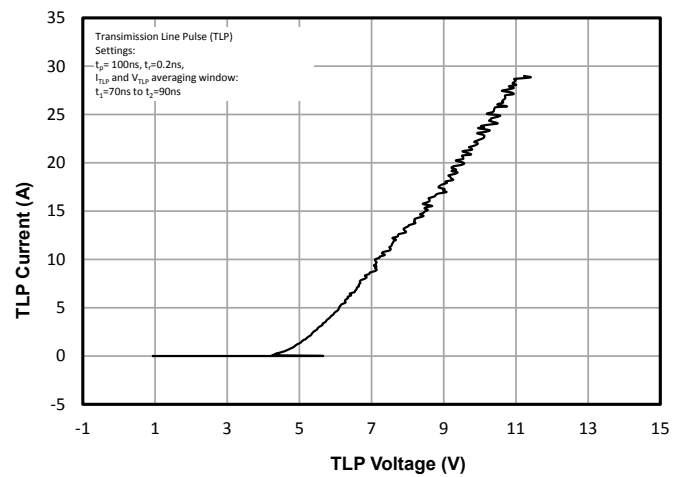
Clamping Voltage vs. Peak Pulse Current ($t_p=8/20 \mu$ s)



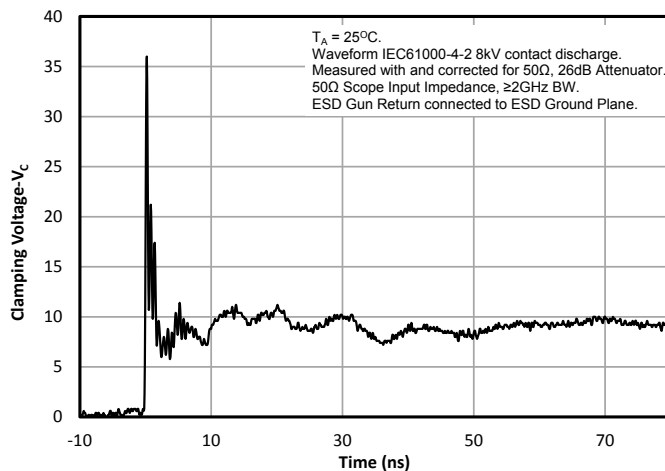
Junction Capacitance vs. Reverse Voltage



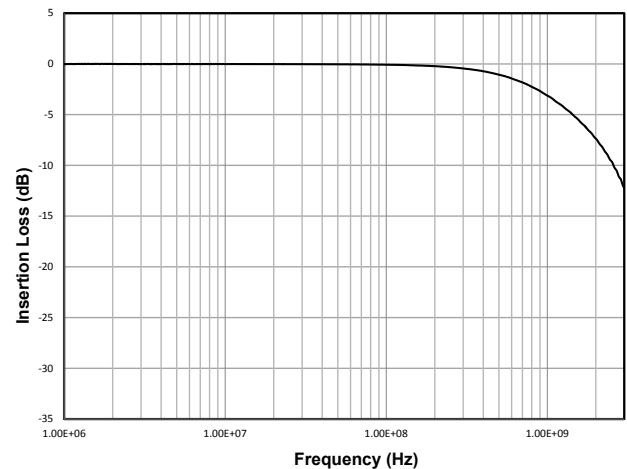
TLP Characteristic



ESD Clamping (+8kV Contact per IEC 61000-4-2)



Typical Insertion Loss (S21)



Application Information

Assembly Guidelines

The small size of this device means that some care must be taken during the mounting process to insure reliable solder joints. The figure at the right details Semtech's recommended mounting pattern. Recommended assembly guidelines are shown in Table 1. Note that these are only recommendations and should serve only as a starting point for design since there are many factors that affect the assembly process. Exact manufacturing parameters will require some experimentation to get the desired solder application.

Solder Stencil

Stencil design is one of the key factors which will determine the volume of solder paste which is deposited onto the land pad. The area ratio of the stencil aperture will determine how well the stencil will print. The area ratio takes into account the aperture shape, aperture size, and stencil thickness. A minimum area ratio of 0.66 is preferred for the subject package. The area ratio of a rectangular aperture is given as:

Area Ratio = (L * W) / (2 * (L + W) * T)

Where:

L = Aperture Length

W = Aperture Width

T = Stencil Thickness

Semtech recommends a stencil with square aperture and rounded corners for consistent solder release. The stencil should be laser cut with electropolished finish. A stencil thickness of 0.075mm (0.003") is recommended. A 0.100mm (0.004") stencil may be used, however the stencil opening may need to be increased slightly to achieve the desired area ratio to ensure proper solder coverage on the pad.

Recommended Mounting Pattern

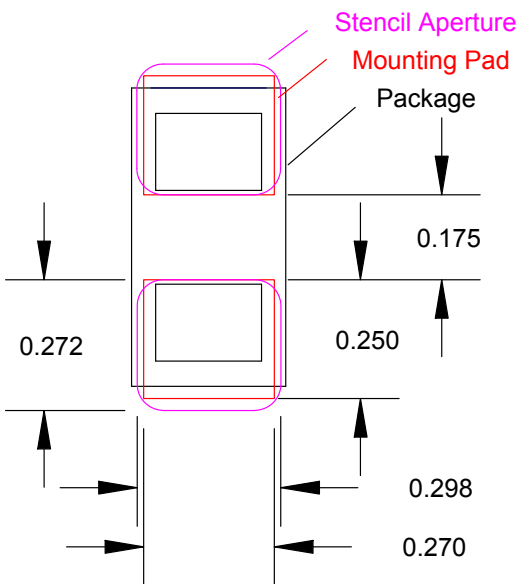
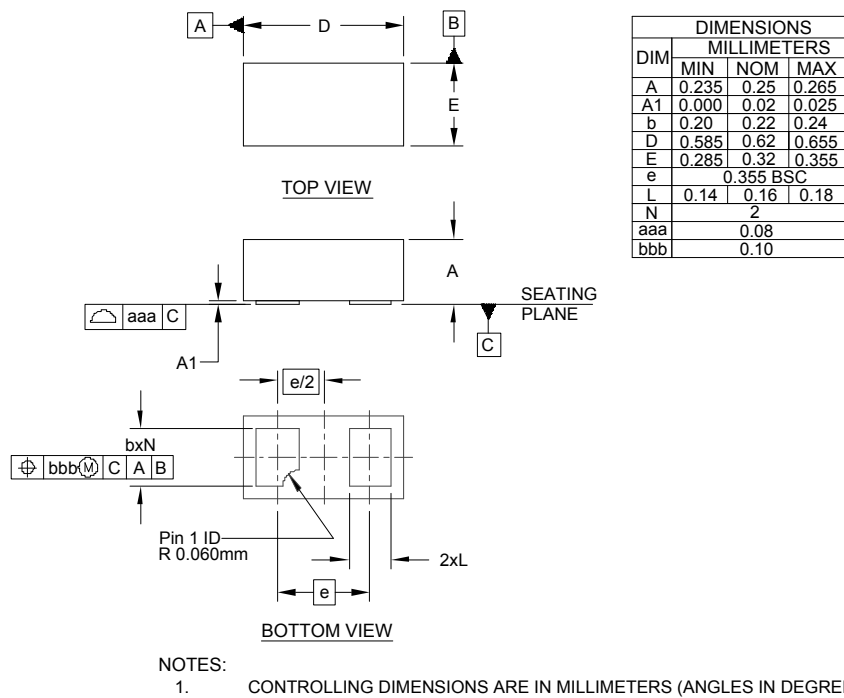


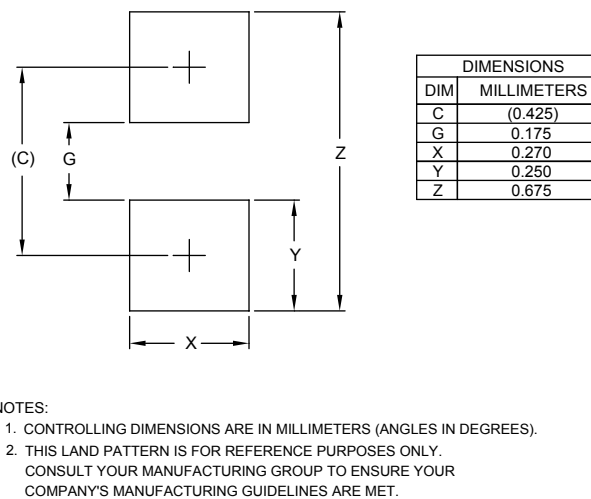
Table 1 - Assembly Guidelines

Assembly Parameter	Recommendation
Solder Stencil Design	Laser Cut, Electro-Polished
Aperture Shape	Rectangular with Rounded Corners
Solder Stencil Thickness	0.075mm (0.003") or 0.100mm (0.004")
Solder Paste Type	Type 4 Size Sphere or Smaller
Solder Reflow Profile	Per JEDEC J-STD-020
PCB Solder Pad Design	Solder Mask Defined
PCB Pad Finish	OSP or NiAu

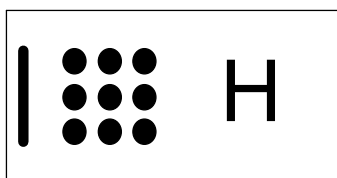
Outline Drawing - SLP0603P2X3A



Land Pattern - SLP0603P2X3A



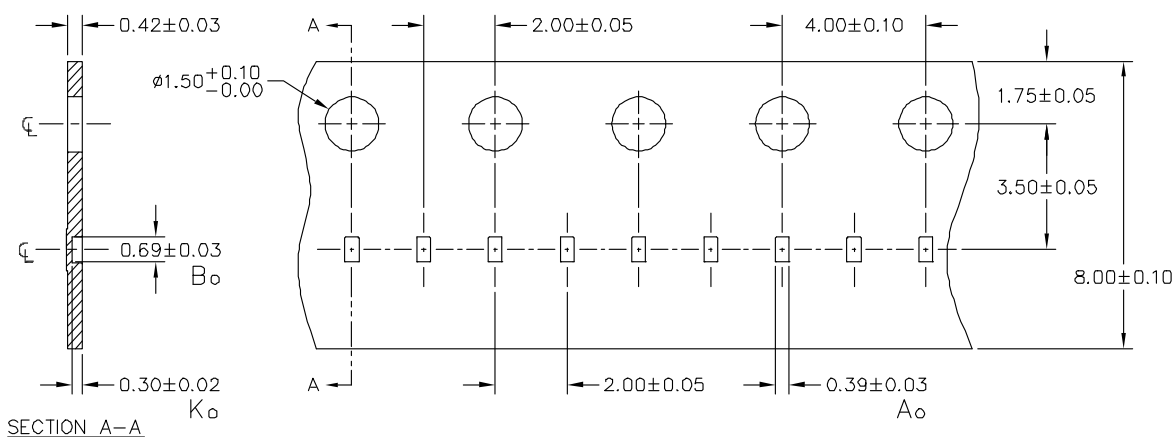
Marking Code



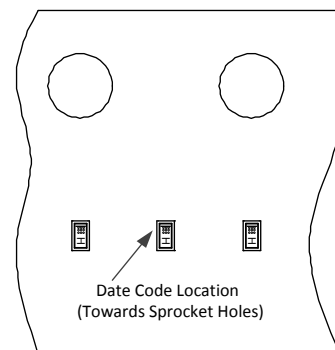
Notes:

1. Dots represent date code matrix and Pin 1 location.

Tape and Reel Specification - Paper Tape



NOTES: ALL DIMENSIONS IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.



Ordering Information

Part Number	Qty per Reel	Reel Size
μ Clamp3311Z.TFT	15,000	7"

Notes:

1. MicroClamp, μ Clamp and μ Clamp are trademarks of Semtech Corporation.



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